



**General  
Semiconductor  
Industries, Inc.**

DLZ-5 THRU 30 SERIES

**DATA  
LINE ZORB®  
TRANSZORB™  
FAMILY**


**FEATURES**

- Multiple TransZorb® TVS Array
- Unidirectional or Bidirectional
- Military Environment Capability
- Dual-In-Line, 16 pin Hermetic Package
- Available with high reliability processing per MIL-S-19500
- $\mu$ P/mP Compatible Package
- Low Capacitance
- Voltage range of 5V to 100V available
- Common Bus Configuration

**MAXIMUM RATINGS**

- 500 Watts Peak Pulse Power/Position (@ 25°C) (8 x 20 $\mu$ s)
- $t_{clamping}$  (0 volts to BV min.) Less than  $1 \times 10^{-12}$  seconds (theoretical) (uni-polar);  $5 \times 10^{-9}$  seconds (bi-polar) (theoretical)
- Operating and Storage Temperatures: -55°C to +150°C
- Forward Surge Rating: 10 Amps, 1/120 sec. @ 25°C (uni-polar)
- Rep Rate (duty cycle): .01%

**MECHANICAL CHARACTERISTICS**

- Ceramic, 16 pin Dual-in-Line Case (.300" row spacing)
- Weight: 3.5 grams (approximate)
- Pin No. 1 marked with flag on lead and dot on top of package. Body marked with Logo  and type Number

**DESCRIPTION**

The TransZorb TVS family of devices is packaged in a dual-in-line, ceramic, hermetically sealed package. Developed specifically for *military environments*, these components offer 15 protective devices; *unidirectional and bidirectional*, common bus connections, per package. The dual-in-line design allows *compatible* packaging for microprocessors, memories, and controllers and is designed specifically for *data line protection*, at the PC board level, TTL and MOS voltages are available for protection of input/output data circuits.

DLZ series TransZorb TVS arrays are available with MIL processing to JANTX equivalent levels per MIL-S-19500. Specify DLZ part number with suffix "-H1" for 100% TX-level screening, and suffix "-H2" for 100% screening with Group B processing. See Appendix B for MIL processing.

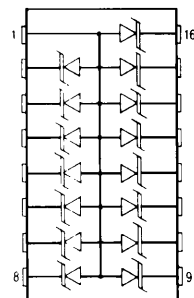
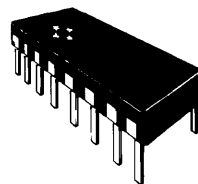
**BENEFITS**

- Saves Space
- Saves Production Time
- Military Compatibility
- Ease of Design
- Protection for Data Lines
- EMP/ESD Protection
- Satisfies Military NEMP requirements
- Protection of I/O Devices

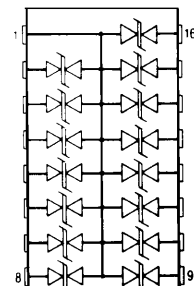
**DEVICE TYPES AVAILABLE**

UNIDIRECTIONAL	BIDIRECTIONAL
DLZ-5, A	DLZ-8C, CA
DLZ-12, A	DLZ-13C, CA
DLZ-17, A	DLZ-19C, CA
DLZ-24, A	DLZ-30C, CA
DLZ-30, A	

**CASE 29**



Typical Uni-polar Schematic



Typical Bi-polar Schematic

FIGURE 1 — Peak Pulse Power vs Pulse Time (per position)

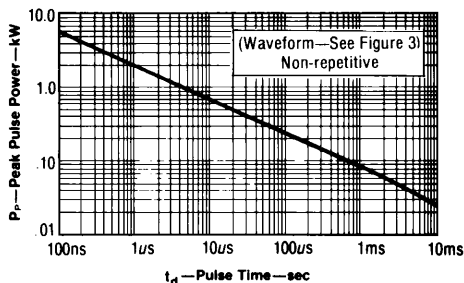
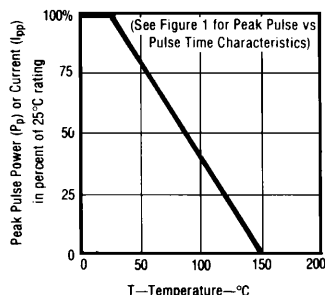


FIGURE 2 — Derating Curve

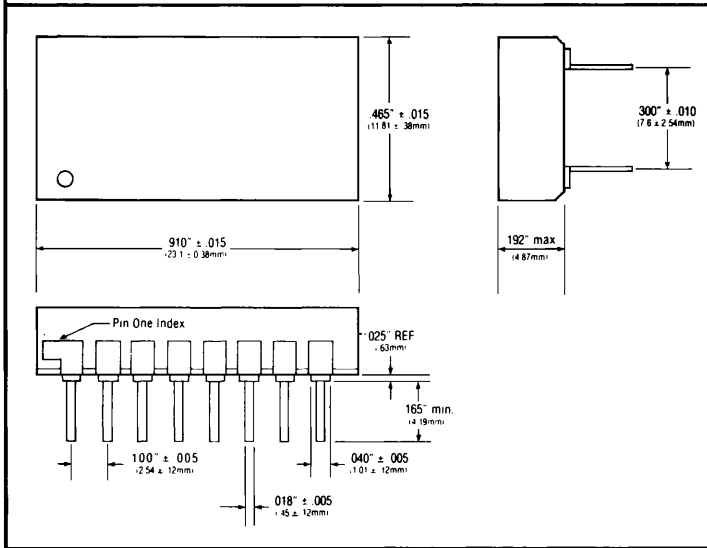


ELECTRICAL CHARACTERISTICS @ 25° C AMBIENT

GENERAL SEMICONDUCTOR PART NUMBER	REVERSE STAND-OFF VOLTAGE VR VOLTS	MINIMUM BREAKDOWN VOLTAGE BV (min) VOLTS	MAXIMUM CLAMPING VOLTAGE @ Ipp1 1A (8 x 20µsec) VC1 VOLTS	MAXIMUM CLAMPING VOLTAGE @ Ipp2 10A (8 x 20µsec) VC2 VOLTS	MAXIMUM REVERSE LEAKAGE @ VR IR µA	MAXIMUM CAPACITANCE @ DV, 1MHz C pF	MAXIMUM VOLTAGE TEMPERATURE VARIATION OF BV MV/°C
<b>UNI-POLAR</b>							
DLZ-5	5	6.0	10.2	12.5	200	880	5
DLZ-5A	5	6.0	9.5	10.6	200	880	5
DLZ-12	12	13.3	21.1	26.0	2	440	18
DLZ-12A	12	13.3	19.1	23.5	2	440	18
DLZ-17	17	19.2	30.4	37.4	2	330	20
DLZ-17A	17	19.2	27.5	33.9	2	330	20
DLZ-24	24	26.7	42.3	52.1	2	275	31
DLZ-24A	24	26.7	38.3	47.2	2	275	31
DLZ-30	30	33.3	52.8	65.0	2	220	39
DLZ-30A	30	33.3	47.8	58.8	2	220	39
<b>BI-POLAR</b>							
DLZ-8C	8	8.5	13.4	16.6	10	440	9
DLZ-8CA	8	8.5	12.2	15.0	10	440	9
DLZ-13C	13	14.4	22.8	28.1	4	385	18
DLZ-13CA	13	14.4	20.6	25.4	4	385	18
DLZ-19C	19	21.6	34.2	42.1	4	275	24
DLZ-19CA	19	21.6	31.0	38.1	4	275	24
DLZ-30C	30	33.3	52.8	65.0	4	165	39
DLZ-30CA	30	33.3	47.8	58.8	4	165	39

\*"A", "CA" suffix denotes selected clamping voltage.

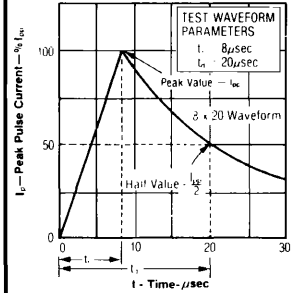
CASE OUTLINE — CASE 29



DLZ-5 THRU 30 SERIES

**DATA LINE ZORB®**  
UNIDIRECTIONAL & BIDIRECTIONAL

FIGURE 3 — Pulse Waveform



NOTES

**Note 1:** A TransZorb is normally selected according to the reverse "Stand Off Voltage" (VR) which should be equal to or greater than the DC or continuous peak operating voltage level.

ABBREVIATIONS & SYMBOLS

- VR** Stand-Off Voltage: Applied Reverse Voltage to assure a nonconductive condition (See Note 1)
- BV(min)** This is the minimum Breakdown Voltage the device will exhibit and is used to assure that conduction does not occur prior to this voltage level at 25°C
- VC(max)** Maximum Clamping Voltage: The maximum peak voltage appearing across the TransZorb when subjected to the peak pulse current in a one millisecond time interval. The peak pulse voltages are the combination of voltage rise due to both the series resistance and thermal rise
- I<sub>pp</sub>** Peak Pulse Current — See Figure 3
- P** Peak Pulse Power
- IR** Reverse Leakage